



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BSC500N20NS3 G	<b>Issued</b>	24. February 2022
<b>MA#</b>	MA005700001		
<b>Package</b>	PG-TDSON-8-1	<b>Weight*</b>	121.35 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.061	2.52	2.52	25227	25227
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		93	
	non noble metal	iron	7439-89-6	0.038	0.03		312	
	non noble metal	copper	7440-50-8	37.762	31.10	31.14	311176	311581
wire	non noble metal	copper	7440-50-8	0.059	0.05	0.05	483	483
encapsulation	organic material	carbon black	1333-86-4	0.082	0.07		678	
	plastics	epoxy resin	-	5.843	4.82		48151	
	inorganic material	silicondioxide	60676-86-0	35.224	29.03	33.92	290264	339093
leadfinish	non noble metal	tin	7440-31-5	1.452	1.20	1.20	11962	11962
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1364	1364
solder	non noble metal	tin	7440-31-5	0.054	0.04		447	
	noble metal	silver	7440-22-4	0.068	0.06		558	
	non noble metal	lead	7439-92-1	2.587	2.13	2.23	21321	22326
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	iron	7439-89-6	0.022	0.02		184	
	noble metal	silver	7440-22-4	1.289	1.06		10626	
	non noble metal	copper	7440-50-8	22.292	18.37	19.46	183695	194560
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	iron	7439-89-6	0.011	0.01		93	
	non noble metal	copper	7440-50-8	11.320	9.33	9.34	93283	93404
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com